## **MOSFET** - Power, Single N-Channel

## 40 V, 0.92 mΩ, 300 A

# NVMFS5C410N

#### Features

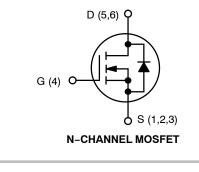
- Small Footprint (5x6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- NVMFS5C410NWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

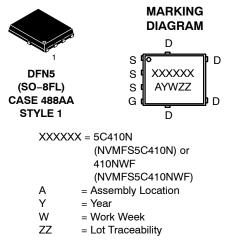


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V <sub>(BR)DS</sub>	; F	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX	
40 V	0.9	92 mΩ @ 10 V	300 A	





#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V <sub>DSS</sub>	40	V
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V
Continuous Drain		$T_{C} = 25^{\circ}C$	I <sub>D</sub>	300	А
Current $R_{\theta JC}$ (Notes 1, 3)	Steady	T <sub>C</sub> = 100°C		212	
Power Dissipation	State	T <sub>C</sub> = 25°C	PD	166	W
R <sub>θJC</sub> (Note 1)		T <sub>C</sub> = 100°C		83	
Continuous Drain Current $R_{\theta JA}$		$T_A = 25^{\circ}C$	I <sub>D</sub>	46	А
(Notes 1, 2, 3)	Steady State	T <sub>A</sub> = 100°C		32	
Power Dissipation		T <sub>A</sub> = 25°C	PD	3.9	W
$R_{\theta JA}$ (Notes 1, 2)		T <sub>A</sub> = 100°C		1.9	
Pulsed Drain Current	$T_A = 25^{\circ}C, t_p = 10 \ \mu s$		I <sub>DM</sub>	900	А
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	–55 to +175	°C
Source Current (Body Diode)			۱ <sub>S</sub>	158	А
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 34 A)			E <sub>AS</sub>	578	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	0.9	°C/W
Junction-to-Ambient - Steady State (Note 2)	R <sub>θJA</sub>	39	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.

3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

#### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

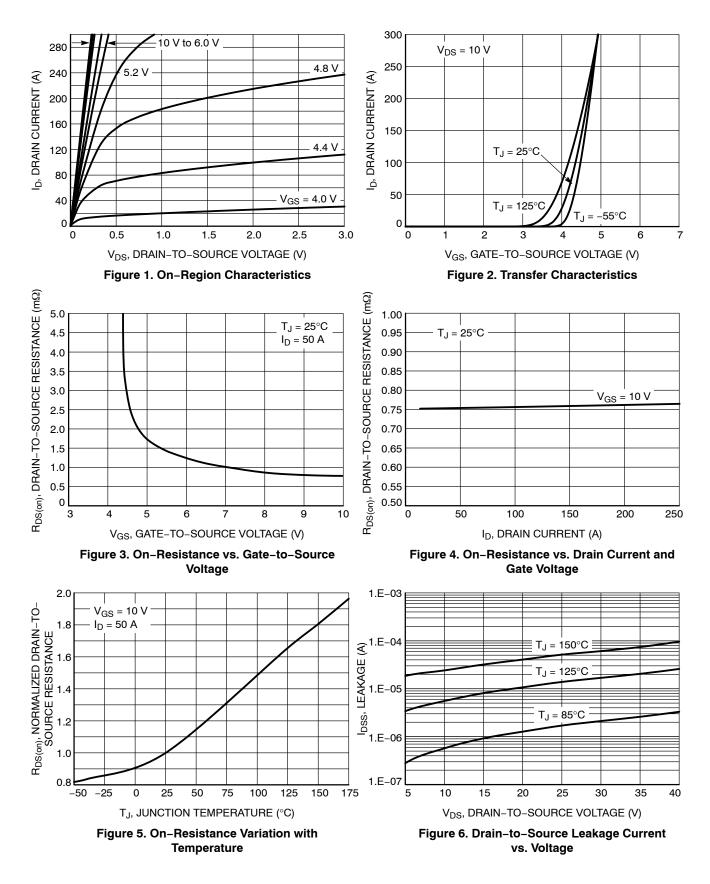
#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS								
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, I <sub>D</sub> = 250 µA		40			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> / T <sub>J</sub>				5		mV/°C	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V,$ $T_{J} = 25 °$				10		
		$V_{DS} = 40 V$	T <sub>J</sub> = 125°C			100	μΑ	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 V, V_G$	<sub>S</sub> = 20 V			100	nA	
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D$	= 250 μA	2.5		3.5	V	
Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				-8.6		mV/°C	
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 50 A		0.76	0.92	mΩ	
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> =15 V, I	<sub>D</sub> = 50 A		190		S	
CHARGES, CAPACITANCES & GATE RE	SISTANCE							
Input Capacitance	C <sub>ISS</sub>				6100			
Output Capacitance	C <sub>OSS</sub>	$V_{GS}$ = 0 V, f = 1 MHz, $V_{DS}$ = 25 V			3400		pF	
Reverse Transfer Capacitance	C <sub>RSS</sub>				70			
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 32 V; $I_{D}$ = 50 A			86			
Threshold Gate Charge	Q <sub>G(TH)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 32 V; I <sub>D</sub> = 50 A			18		nC	
Gate-to-Source Charge	Q <sub>GS</sub>				28			
Gate-to-Drain Charge	Q <sub>GD</sub>				14			
Plateau Voltage	V <sub>GP</sub>				4.9		V	
SWITCHING CHARACTERISTICS (Note 5	5)							
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 32 V, I <sub>D</sub> = 50 A, R <sub>G</sub> = 2.5 Ω			54		- ns	
Rise Time	tr				162			
Turn–Off Delay Time	t <sub>d(OFF)</sub>				227			
Fall Time	t <sub>f</sub>				173			
DRAIN-SOURCE DIODE CHARACTERIS	TICS				•			
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V,	$T_J = 25^{\circ}C$		0.8	1.2		
	$I_{\rm S} = 50  \text{A}$	T <sub>J</sub> = 125°C		0.65		V		
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, dIS/dt = 100 A/µs, I <sub>S</sub> = 50 A			91		ns	
Charge Time	t <sub>a</sub>				42			
Discharge Time	t <sub>b</sub>				49			
Reverse Recovery Charge	Q <sub>RR</sub>				159		nC	

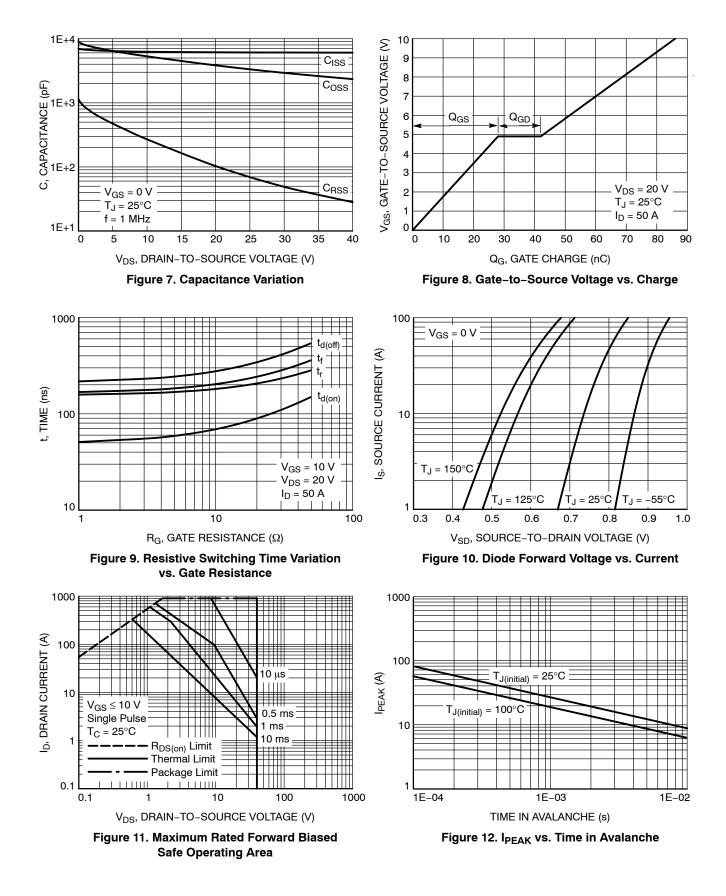
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width  $\leq 300 \ \mu$ s, duty cycle  $\leq 2\%$ .

5. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**



#### **TYPICAL CHARACTERISTICS**



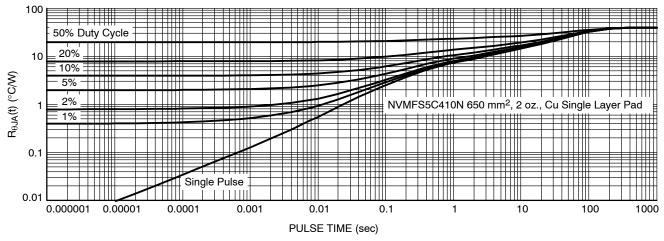


Figure 13. Thermal Characteristics

#### **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NVMFS5C410NT1G	5C410N	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5C410NWFT1G	410NWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel
NVMFS5C410NT3G	5C410N	DFN5 (Pb-Free)	5000 / Tape & Reel
NVMFS5C410NWFT3G	410NWF	DFN5 (Pb-Free, Wettable Flanks)	5000 / Tape & Reel
NVMFS5C410NAFT1G	5C410N	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5C410NWFAFT1G	410NWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





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